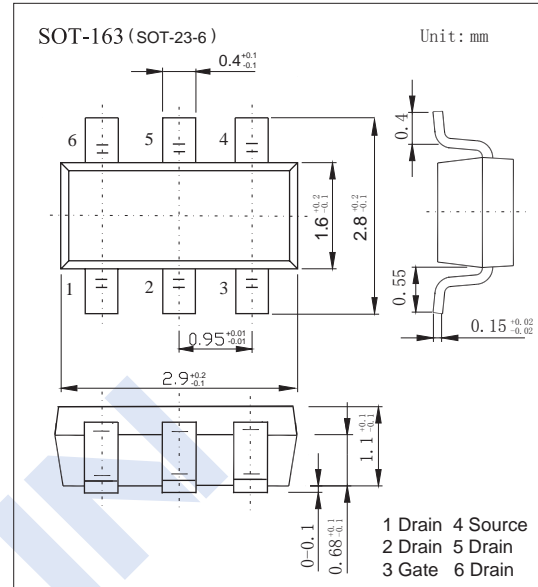
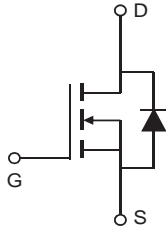


N-Channel MOSFET

2KK5032

■ Features

- $V_{DS} = 30V$
- $I_D = 6.5 A$ ($V_{GS} = 10V$)
- $R_{DS(ON)} < 25m\Omega$ ($V_{GS} = 10V$)
- $R_{DS(ON)} < 35m\Omega$ ($V_{GS} = 4.5V$)



■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	$T_A = 25^\circ C$	A
		$T_A = 70^\circ C$	
Pulsed Drain Current	I_{DM}	27	W
Power Dissipation	P_D	$T_A = 25^\circ C$	
		$T_A = 70^\circ C$	1.5
Thermal Resistance.Junction- to-Ambient	R_{thJA}	$t \leq 10s$	$^\circ C/W$
		Steady-State	
Thermal Resistance.Junction- to-Lead	R_{thJL}	30	$^\circ C$
Junction Temperature	T_J	150	
Storage Temperature Range	T_{stg}	-55 to 150	

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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
Drain-Source Breakdown Voltage	V _{DSS}	I _D =250 μA, V _{GS} =0V	30			V	
Zero Gate Voltage Drain Current	I _{DSS}	V _D =30V, V _{GS} =0V			1	μA	
		V _D =30V, V _{GS} =0V, T _J =55°C			5		
Gate-Body Leakage Current	I _{GSS}	V _D =0V, V _{GS} =±20V			±100	nA	
Gate Threshold Voltage	V _{GS(th)}	V _D =V _{GS} , I _D =250 μA	1.2		2.4	V	
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =5A			25	mΩ	
		V _{GS} =10V, I _D =5A, T _J =125°C			43		
		V _{GS} =4.5V, I _D =4A			35		
Forward Transconductance	g _{FS}	V _D =5V, I _D =5A		8		S	
Input Capacitance	C _{iss}	V _{GS} =0V, V _D =15V, f=1MHz		270		pF	
Output Capacitance	C _{oss}			50			
Reverse Transfer Capacitance	C _{rss}			35			
Gate Resistance	R _g	V _{GS} =0V, V _D =0V, f=1MHz	1.4		4.2	Ω	
Total Gate Charge (10V)	Q _g	V _{GS} =10V, V _D =15V, I _D =5A		6.3	12	nC	
Total Gate Charge (4.5V)				3.2	8		
Gate Source Charge			Q _{gs}		0.65		
Gate Drain Charge			Q _{gd}		1.75		
Turn-On DelayTime	t _{d(on)}	V _{GS} =10V, V _D =15V, R _L =3Ω, R _G =3Ω		3		ns	
Turn-On Rise Time	t _r			2.5			
Turn-Off DelayTime	t _{d(off)}			17.5			
Turn-Off Fall Time	t _f			2.5			
Body Diode Reverse Recovery Time	t _{rr}	I _F =5A, di/dt=100A/μs		10		nC	
Body Diode Reverse Recovery Charge	Q _{rr}			2.3			
Maximum Body-Diode Continuous Current	I _S				3	A	
Diode Forward Voltage	V _{SD}	I _S =1A, V _{GS} =0V			1	V	

* The static characteristics in Figures 1 to 6 are obtained using <300us pulses, duty cycle 0.5% max.

■ Marking

Marking	KBF
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N-Channel MOSFET 2KK5032

■ Typical Characteristics

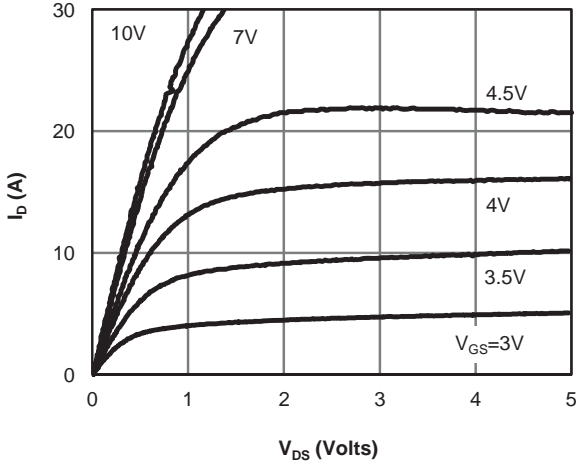


Figure 1: On-Region Characteristics (Note E)

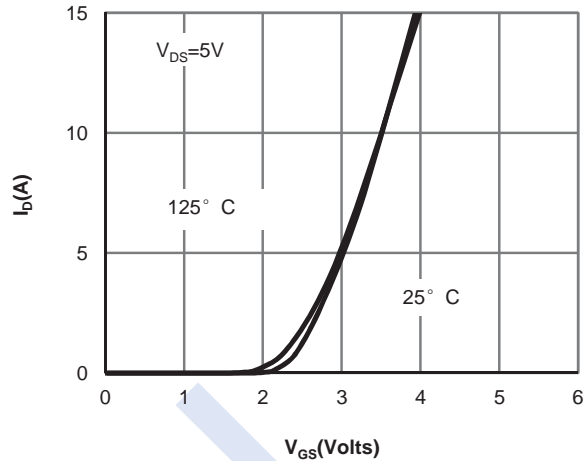


Figure 2: Transfer Characteristics (Note E)

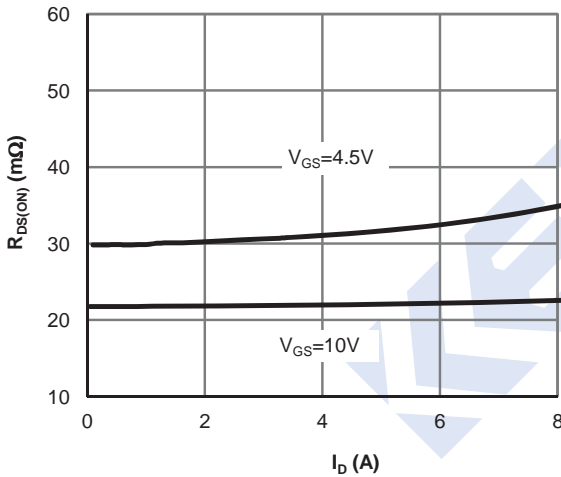


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

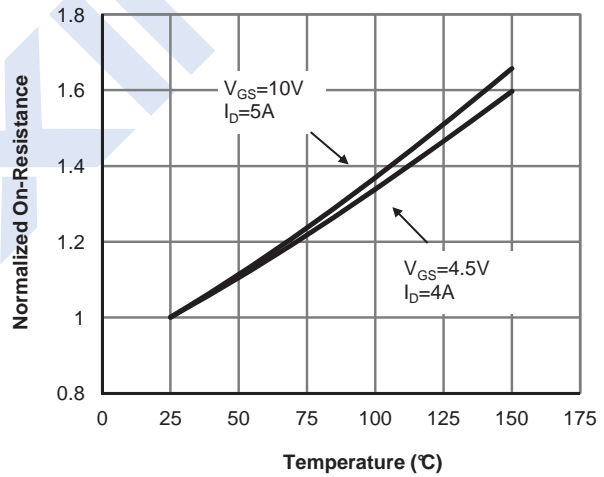


Figure 4: On-Resistance vs. Junction Temperature (Note E)

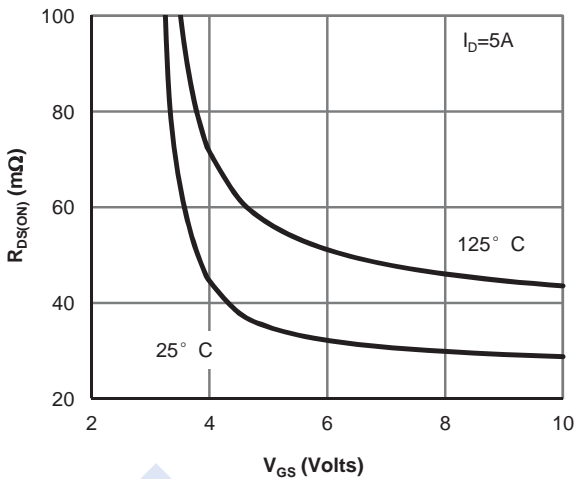


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

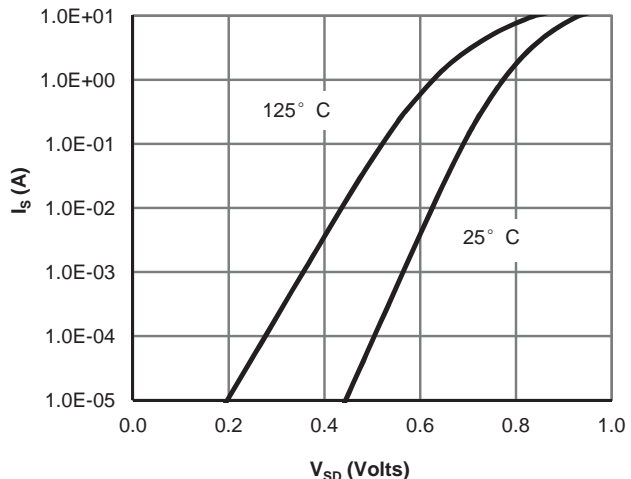


Figure 6: Body-Diode Characteristics (Note E)

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■ Typical Characteristics

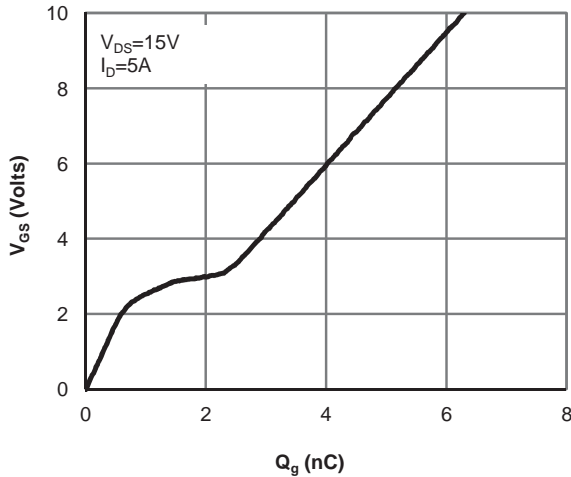


Figure 7: Gate-Charge Characteristics

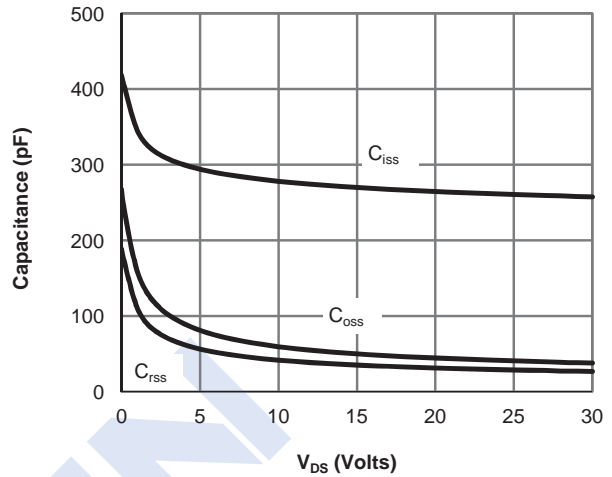


Figure 8: Capacitance Characteristics

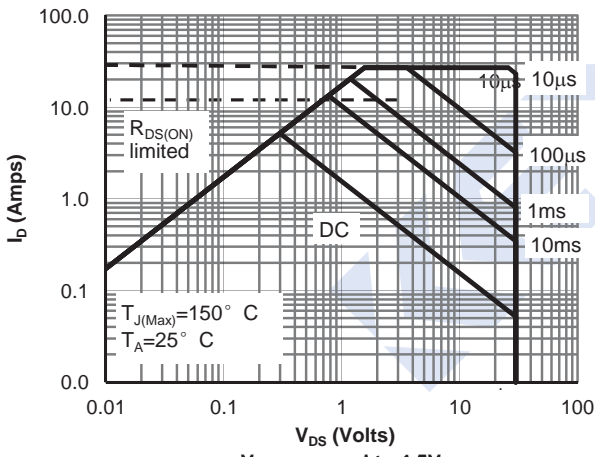


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

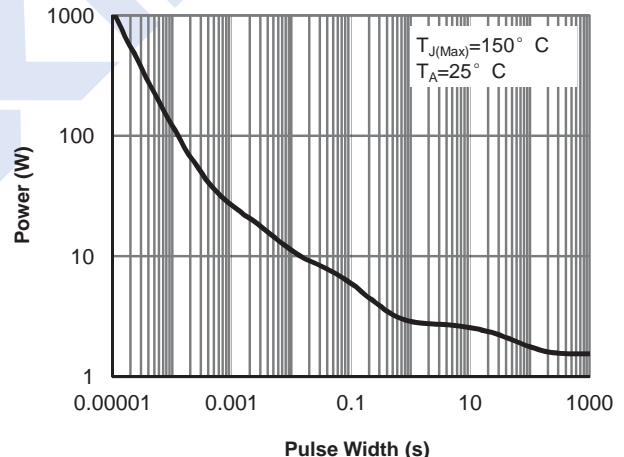


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

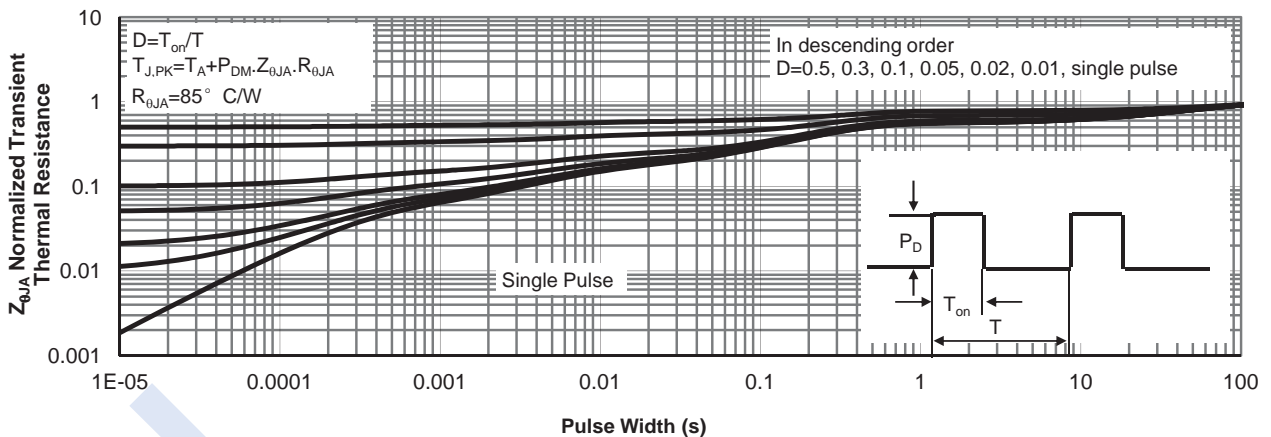


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)